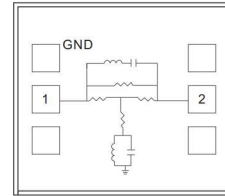


### Performance

- Frequency: 1.7~2.7GHz
- Insertion Loss:  $\leq 1.0$ dB
- Attenuation: 3.0dB
- Impedance: 50 $\Omega$
- Chip size: 0.82\*0.89\*0.1 mm

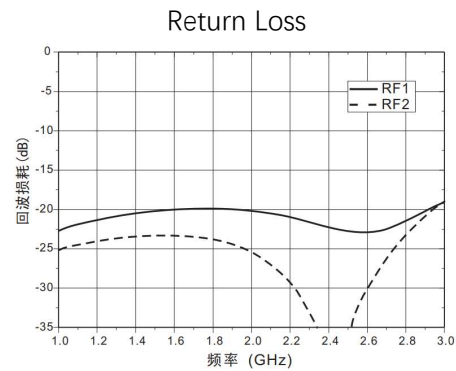
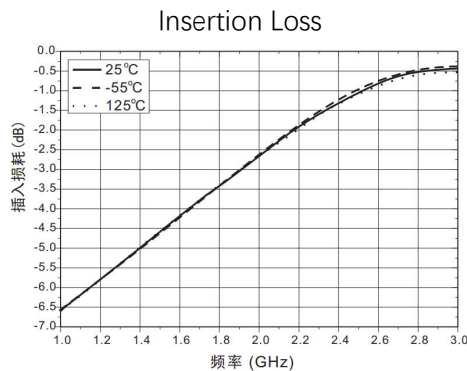
### Function Diagram



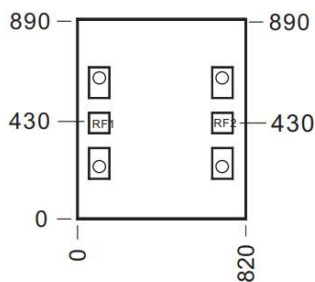
### Electrical Specifications (TA=+25°C, 50 $\Omega$ system)

Parameter	Min	Typical	Max	Unit
Frequency Range	1.7~2.7			GHz
Insertion Loss	-	0.8	1.0	dB
Attenuation	-	3.0	-	dB
Input Return Loss	17	22	-	dB
Output Return Loss	20	25	-	dB

### Test Curves (Die chip test)



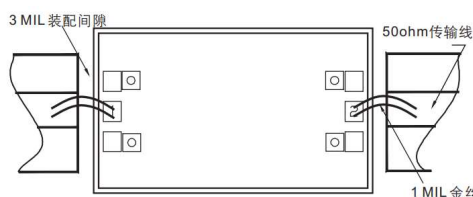
### Outline Size



### Note:

1. Unit:  $\mu\text{m}$
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated  
Pads size: 100\*100  $\mu\text{m}$
5. Don't bonding on thru holes
6. Tolerance:  $\pm 50\mu\text{m}$

### Assembly Drawing



### Bonding Pads Definition

Number	Symbol	Description
RF1、RF2	RF Ports	RF ports, 50 ohm impedance
	GND	Bottom side of chip must be grounded

**Absolute Max. Ratings**

Static Protection Grade	Class 1A
Input Power	30 dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C



**ELECTROSTATIC SENSITIVE DEVICE**  
**OBSERVE HANDLING PRECAUTIONS**